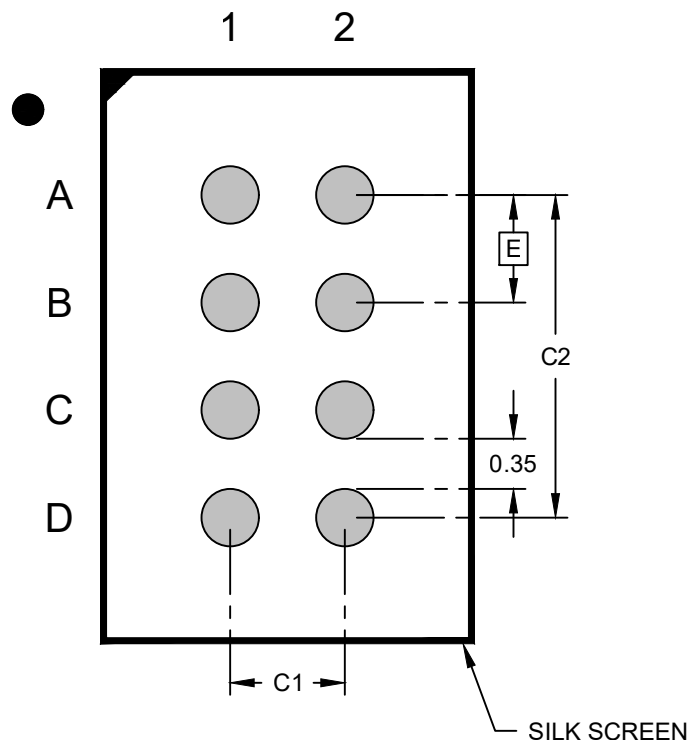


8-Ball Very-Thin Fine-Pitch Ball Grid Array (E9B) 2.35x3.73x1.0mm [VFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packageing>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.75 BSC		
Contact Pad Spacing	C1		0.80	
Contact Pad Spacing	C2		2.25	
Contact Pad Diameter (Xnn)	X			0.30
Contact Pad to Contact Pad (Xnn)	G2	0.35		

Notes:

- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, please refer to current industry standard IPC-7093.